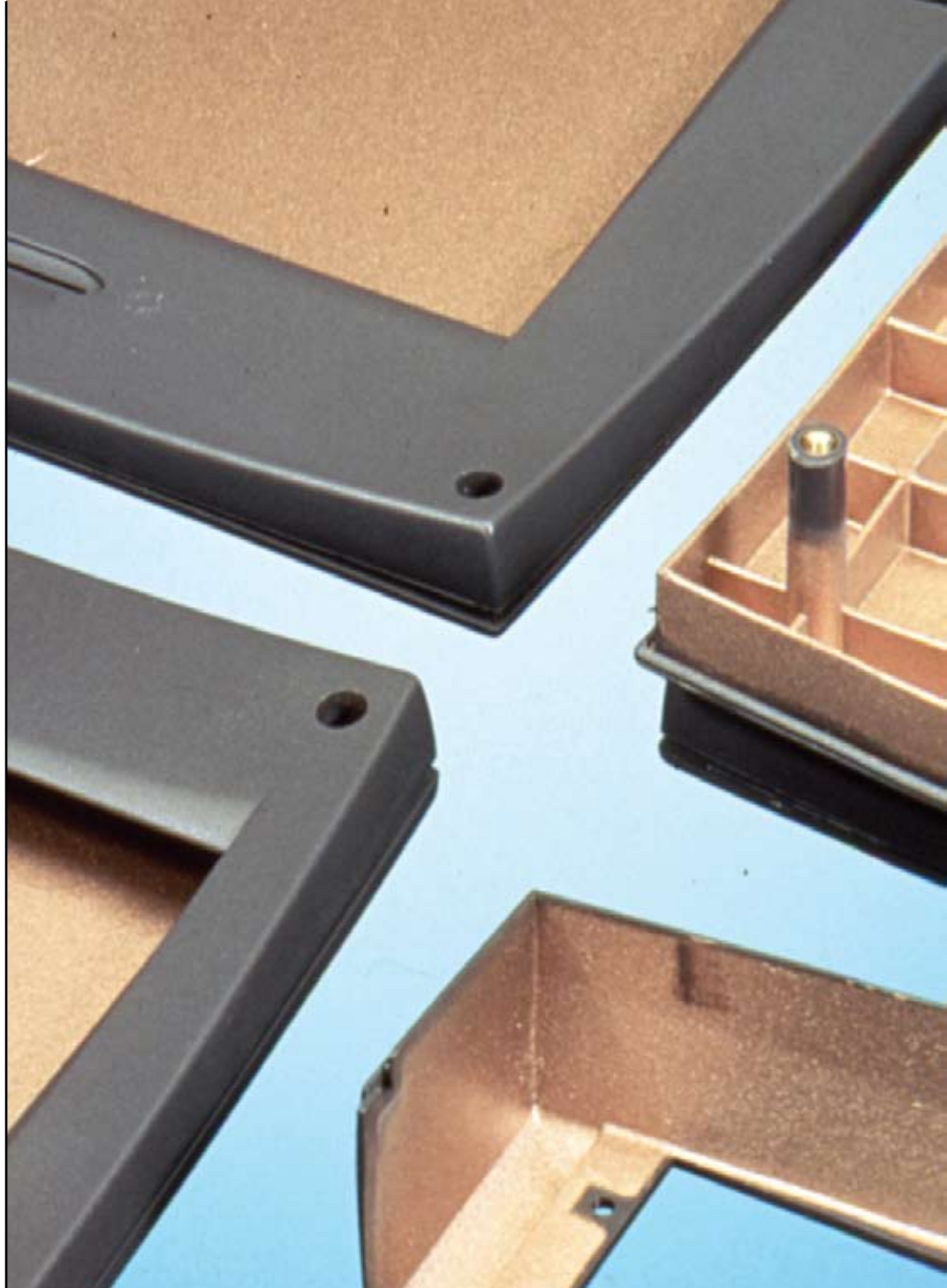


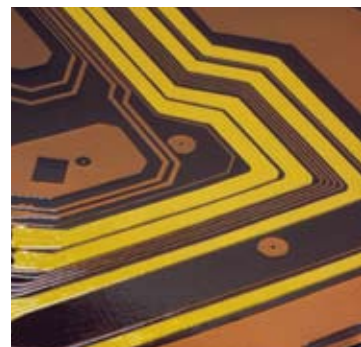


aerospace
climate control
electromechanical
filtration
fluid & gas handling
hydraulics
pneumatics
process control
sealing & shielding



Conductive Compounds

Additional Materials Selector Guide



Conductive Compounds Selector Guide - Additional Offerings

	Family	Product	Filler	Resin Type (Parts)	Specific Gravity ¹⁸	Max. Vol. Resistivity ¹⁸	Max. Surface Resistance ¹⁸ @ (Rec. Thickness ¹⁷)	Min. Lap Shear ¹⁸	Elevated Cure Schedule	RT Cure Schedule	Working Life	Shelf Life	Suggested Primer ¹²	Packing Size		Theoretical Coverage @ (Rec. Thickness ¹⁷)		VOC ⁷	Hazardous Shipping Required ⁸	Samples Availability	Typical Application	Comments	
														U.S. ²¹	Metric	ft ² /g (mils)	m ² /g (μ)						g/L
					g/mL	ohm-cm	ohm/sq. (mils)	psi	kPa	Time @ °F [°C]	Time	Minutes	Months							Note ⁹			
Conductive Adhesives	CHO-BOND	592	Ag	Epoxy [2] [A]:[B] 100:50	2.6	0.050	n/a	1500	10342	0.50 hr. @ 212°F (100°C)	1 week ⁴	240	9 ¹¹	n/a	3 oz. & 1 lb.	85 & 454 g	n/a (1)	n/a (25)	160	Yes	+	Bonding enclosures	General purpose; nearly liquid; 0.025 - 0.127 mm bond lines; bonds dissimilar metals
	TECKNIT	0008	Ag/glass	Epoxy [2] [A]:[B] 100:140	1.9	0.020	n/a	1000	6895	0.50 hr. @ 212°F (100°C) & 24 hr. @ RT	n/a	45	15	n/a	1 lb.	454 g	n/a	n/a	16	Yes	+	Bonding enclosures	General purpose; accelerated cure only; less expensive & less conductive filler
	CHO-BOND	360-208	Ag/Cu & Ag	Epoxy [2] [360],[208] 100:33.33	4.0	0.010	n/a	1400	9653	0.75 hr. @ 212°F (100°C) ²⁰	24 hr.	60	9 ¹¹	1086	3 oz. & 1 lb.	85 & 454 g	n/a (10)	n/a (254)	0	No	+	Bonding enclosures	Similar to 360-20, but requires no contact pressure for cure; less conductive
Conductive Sealants	CHO-BOND	4669	Ag/Cu	Polyisobutylene (1)	2.0	0.080	n/a	n/a	n/a	n/a	1 week ⁴	150	6 ¹¹	n/a	4 oz. & 1.5 lb. ¹⁵	113.4 & 681 g	n/a (15)	n/a (381)	340	Yes	+	Sealing enclosure seams; airframe gap sealing	Good performance in vibration or shear
Conductive Silicone Sealants/Adhesives	CHO-BOND	1121	Ag/Cu	Silicone (1)	3.6	0.010	n/a	150	1034	n/a	1 week ⁴	30	12	1086 ⁵	1 lb. ¹⁶	454 g	n/a (7)	n/a (178)	0	Yes	+	Sealing enclosure seams; airframe gap sealing; connector shielding	Xylene-free version of CHO-BOND 1038; rec. bond line thickness: > 0.18 mm; primer promotes adhesion
	TECKNIT	0192 & 0193 ¹	Ag/Cu	Silicone (1)	3.8	0.040	n/a	200	1379	n/a	1 week ⁴	n/a	9	0239 ⁵	3.5 oz. & 14 oz.	99 & 396.9 g	n/a (10)	n/a (254)	0	Yes	+	Bonding Ag/Cu elastomer gaskets; thin bond gaps	Rec. bond line thickness: < 0.4 mm; flexible paste
	TECKNIT	0014	Ag/glass	Silicone (1)	2.0	0.010	n/a	25	172	n/a	24 hr.	n/a	9	n/a	1 lb.	454 g	n/a (7)	n/a (178)	206	Yes	+	Bonding enclosures; repair of damaged gaskets	Flexible, fast cure silicone caulk
	TECKNIT	0236	Ag/Al	Silicone [2] [A]:[B] 100:2.04	1.9	0.010	n/a	100	689	24 hr. @ RT + 24 hr. @ 212°F (100°C)	1 week ⁴	n/a	9	n/a	1 lb.	454 g	n/a	n/a	259	Yes	+	Bonding Ag/Al elastomers	Thick flexible paste
	CHO-BOND	1016	Ni/C	Silicone (1)	2.2	0.950	n/a	150	1034	n/a	1 week ⁴	30	9	1086 ⁵	2.5 oz. & 10 oz. ¹⁴	70.9 & 283.5 g	n/a (10)	n/a (254)	0	Yes	+	Sealing enclosure seams; airframe gap sealing; connector shielding	Ideal in outdoor applications for EMI shielding and low corrosion
	TECKNIT	0350 & 0355 ¹	Ni/C	Silicone (1)	2.6	0.500	n/a	100	689	n/a	1 week ⁴	n/a	9	1086 ⁵	2.5 oz. & 10 oz.	70.9 & 283.5 g	n/a (10)	n/a (254)	0	Yes	+	Bonding Ni/C elastomers; thin bond gaps	Rec. bond thickness: < 0.4 mm; flexible paste
	TECKNIT	0035	Ni	Silicone [2] [A]:[B] 100:2.53	4.0	0.010	n/a	50	345	24 hr. @ RT & 24 hr. @ 212°F (100°C)	1 week ⁴	240	9	n/a	1 lb.	454 g	n/a (10)	n/a (254)	285	Yes	+	Bonding elastomer gaskets	Thin flexible paste
Conductive Greases	CHO-LUBE	4220	Ag	Silicone (1)	3.1	0.100	n/a	n/a	n/a	n/a	n/a	n/a	12	n/a	4 oz. & 10 oz. ¹⁴	113.4 & 283.5 g	n/a (1)	n/a (25)	0	No	-	Grounding	Excellent for surface-to-surface contact areas
	TECKNIT	0015 & 0016 ¹	Ag/glass	Silicone (1)	2.5	0.20	n/a	n/a	n/a	n/a	n/a	n/a	12	n/a	2 oz. & 1 lb.	56.7 & 454 g	n/a (1)	n/a (25)	0	No	-	Electrical grounding and lubricating	Contains no carbon or graphite
Conductive Coatings	TECKNIT	0025 & 0081 ¹	Ag/glass	Acrylic (1)	1.7	n/a	1.000 (2)	n/a	n/a	n/a	1 week	30	6	n/a	1 lb. & 1 gal.	454 & 3632 g	0.110 (2)	0.0102 (51)	567	Yes	+	Conductive coatings on enclosures	Thinning required for spraying, toluene is recommended
	CHO-SHIELD	611	Ag	Epoxy [2] [A]:[B] 100:36	1.8	n/a	0.060 (1)	n/a	n/a	1 hr. @ 250°F (121°C)	1 week	480	9 ¹¹	n/a	1 lb.	454 g	0.110 (1)	0.0102 (25)	517	Yes	-	Protecting EMI flanges	Variant of CHO-SHIELD 596
	CHO-SHIELD	598	Ag	Epoxy [2] [A]:[B] 100:25	1.9	n/a	0.060 (1.5)	n/a	n/a	1 hr. @ 75°F (24°C) + 1 hr. @ 150°F (66°C) + 1 hr. @ 250°F (121°C)	2 week	480	9 ¹¹	n/a	1 lb.	454 g	0.110 (1.5)	0.0102 (37)	439	Yes	-	Protecting EMI flanges	Exceptional salt spray resistance
	CHO-SHIELD	610	Ag/Cu	Epoxy [2] [A]:[B] 100:28.25	1.2	n/a	0.150 (2)	n/a	n/a	2 hr. @ RT + 4 hr. @ 175°F (79°C)	1 week	480	9 ¹¹	n/a	1 gal.	3750 g	0.060 (2)	0.0056 (25)	591	Yes	+	Plastic enclosure shielding	Corrosion protection
	CHO-FLEX	601	Ag	Polyurethane (1)	2.0	n/a	0.060 (1)	n/a	n/a	1.5 hr. @ 360°F (182°C)	n/a	n/a	6 ¹¹	n/a	1 lb.	454 g	0.066 (1)	0.0061 (25)	422	Yes	-	Round wire cable shielding; flexible circuit cable shielding	Screenable flexible circuit
	TECKNIT	7308 ²	Ag	Polyurethane [2] [A]:[B] 100:32.45	1.8	n/a	0.060 (2)	n/a	n/a	n/a	1 week	30	9	n/a	12 oz.	340 g	0.114 (2)	0.0106 (51)	658	Yes	+	Conductive coatings on enclosures	Thinning not required for spraying
	CHO-SHIELD	4998	Ag	Polyurethane [3] [A]:[B]:[C] 100:17.18:14.51	2.1	n/a	0.075 (1)	n/a	n/a	2 hr. RT & 40-60% RH + 2 hr. @ 130°F (55°C)	24 hr.	60	6	n/a	1 gal.	7200 g	0.104 (1)	0.0097 (25)	596	Yes	-	Aircraft coatings; grounding	Very smooth and very conductive; excellent sprayability
	CHO-SHIELD	4076	Ni	Polyurethane (1)	1.0	n/a	0.500 (2)	n/a	n/a	n/a	24 hr.	n/a	12	n/a	1 gal.	6100 g	0.016 (2)	0.0015 (51)	477	Yes	-	Room shielding	Adheres to plaster, wood, glass, concrete, drywall and most metals
Conductive Inks	CHO-FLEX	4430	Ag	Polyester (1)	2.5	n/a	0.080 (0.5)	n/a	n/a	0.5 hr. @ 250°F (121°C)	n/a	n/a	9 ¹¹	n/a	1 lb.	454 g	0.046 (0.5)	0.0043 (13)	510	Yes	+	Membrane keyboard and sensor application	Bonds to Mylar® films; can be creased or scratched without affecting performance
Conductive Primers ¹²	CHO-BOND	1085	n/a	n/a	0.82	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	6	n/a	1 pt.	400 g	n/a	n/a	744	Yes	-	Primer for Cho-Bond 1029	n/a
	CHO-BOND	1086	n/a	n/a	0.80	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	9	n/a	0.35 oz. & 1 pt.	10 & 375 g	n/a	n/a	740	Yes	-	Primer for moisture cured silicone	n/a
	TECKNIT	0239	n/a	n/a	0.76	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	9	n/a	0.5 pt.	180 g	n/a	n/a	625	Yes	-	Primer for TECKNIT 0192 & 0193	n/a
	CHO-BOND	1091	n/a	n/a	0.80	n/a	n/a	n/a	n/a	n/a	0.5 hr.	n/a	6	n/a	0.25 & 0.5 pt.	94 & 188 g	n/a	n/a	797	Yes	-	Primer for CHO-SHIELD 2000 series coatings on aluminum	n/a

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Additional facilities:

Hudson, NH; Guadalajara & Monterrey, Mexico; Oulu, Finland; Sadska, Czech Republic; Tianjin, China; Chennai, India.

NOTES:

- Two part numbers are listed which represent the same material in a different sized containers.
- Formerly known as 73-00008.
- Value represents DC resistance through a 0.4 square inch by 0.008 inch thick sample.
- Material is sufficiently cured after 24 hours for handling purposes. Full specification properties are developed after time given.
- Primer included with product.
- CHO-SHIELD 2003 packaging is irregular. The "-00-" size contains 250 g of CHO-SHIELD 2003 and includes 94 g of CHO-BOND 1091 primer.
The "-01-" size contains 524 g coating and includes 94 g primer.
The "-04-" size contains 700 g coating and includes 188 g primer.
- Volatile Organic Content (VOC) values are theoretical approximations calculated from the characteristics of the components in the product as we know them at this time.
- All compounds such as these should be packed and shipped by trained professionals. Regulations vary by material type and by quantity. The information provided here is to be used as a general guideline only.
- Samples availability scale: +++ represents high sample availability with short lead times; + represents samples available for qualified applicants or with potentially long lead times; - represents that samples are generally not available unless in very specific instances.
- CHO-BOND 584-29 is sold in 1, 2 & 10 gram ChoPaks; a 3 gram dual syringe package, bundle of 10; plus 3 oz. (85 g) & 1 lb. (454 g) bulk kits.
- The shelf life of this product may be extended with testing, generally 3 additional months from the original expiration date. Contact Chomerics for details. Customer will need to submit an unused container or kit for testing and a fee will apply.
- Primers are applied to the substrate prior to application of the conductive material. In no instance is the primer to be mixed into the conductive material.
- Packed in a small aluminum tube.
- Small size packed in a small aluminum tube; large size packed in a 6 fluid ounce Semco tube.
- Small size packed in a small aluminum tube; large size packed in a 12 fluid ounce cartridge.
- Packed in a 6 fluid ounce Semco tube.
- The recommended thickness may vary from application to application. Please use the published data as an initial guideline. Contact Chomerics' Application Engineering for assistance.
- Properties listed are for products prepared at the elevated cure schedule. Test Methods: Specific Gravity, 95-40-5504, 95-40-5502; Volume Resistivity, 95-40-5102, 95-40-5101, 95-40-6007, 95-40-6017; Surface Resistance, 95-40-5104; Lap Shear, 95-40-5300.
- Alternative cure: 2 hrs. @ 150°F (65°C) or 0.75 hr. @ 210°F (99°C).
- Alternative cure: 0.25 hr. @ 235°F (115°C); 1 hr. @ 200°F (95°C) or 2 hrs. @ 150°F (65°C).
- Ounces [oz.] are weight-based, i.e., 0.0625 pound or 28.4 grams. Some conductive coatings are in volume-based units of gallons, quarts and pints.

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SG 1003 EN October 2008 Rev B

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